

2814
E
&
A
EDWARDS & ANGELL, LLP

COUNSELLORS AT LAW
since 1894

DIKE, BRONSTEIN, ROBERTS & CUSHMAN
Intellectual Property Practice Group

MARLBOROUGH, MA OFFICE
TELEPHONE (508) 485-7772

WASHINGTON, DC
TELEPHONE (703) 553-2563

MAILING ADDRESS:
P.O. BOX 9169
BOSTON, MA 02209

101 FEDERAL STREET
BOSTON, MA 02110
(617) 439-4444
FAX (617) 439-4170

FACSIMILE TRANSMITTAL

DATE: February 12, 2002

TO: U.S. Patent & Trademark Office
Examining Group 2800

FAX NO.: 1-703-872-9318

FROM: Steven M. Jensen

FAX NO.: 617-439-4170

Our Docket No.: 55413 (71987)

No. of Pages (incl. cover): 5

Re: U.S. Serial Number 09/718,669

MESSAGE:

Please enter the attached Amendment.

NOTICE

The message and/or information which accompanies this facsimile cover sheet is intended for the addressee named above only. If you are not the intended recipient, please contact the sender by collect telephone at the number indicated. You will be advised regarding the disposition of what you have received. The mis-delivery of the message and/or information which accompanies this facsimile cover sheet is not intended to be and shall not constitute a disclosure of trade secrets, of attorney work product or of an attorney-client communication. No waiver of any privilege is intended. Thank you for your attention to this matter.

BOSTON HARTFORD NEWPORT NEW YORK PALM BEACH PROVIDENCE SHORT HILLS

Docket No. 55413 (71987)

#5/a
2/20/02
Searle

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: P. Yuan et al.
U.S.S.N.: 09/718,669 GROUP: 2814
FILED: November 22, 2000 EXAMINER: D. Nguyen
FOR: TAPE CARRIER PACKAGE STRUCTURE WITH DUMMY PADS
AND DUMMY LEADS FOR PACKAGE REINFORCEMENT

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to Group 2800 of the U.S. Patent & Trademark Office by facsimile number 703-872-9318 on February 12, 2002.

By:

Steven M. Jensen

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated December 3, 2001 of the above-referenced application. Please amend the application as follows.

IN THE SPECIFICATION

On page 1, lines 25-26, please delete the paragraph.

On page 2, lines 11-14, please amend the paragraph as follows:

Referring further to FIG. 1C, in the next step, an encapsulation process is performed to dispense an encapsulation material, such as resin, through the gaps between the inner leads 130 into the device hole 120a so as to form an encapsulation body 140 to encapsulate the semiconductor chip 110.